

Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Blocking Voltage	350	V _P
Reverse Input Voltage	5	V
Input control Current	50	mA
Peak (10ms)	1	A
Input Power Dissipation ¹	70	mW
Total Power Dissipation ²	400	mW
Isolation Voltage, Input to Output	1500	V _{rms}
Operational Temperature, Ambient	-40 to +85	°C
Storage Temperature	-40 to +125	°C

¹ Derate linearly 1.33 mW / °C

² Derate output power linearly 3.33 mW / °C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

Electrical Characteristics @ 25°C

Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics						
Blocking Voltage	I _L =1μA	V _{DRM}	350	-	-	V
Load Current						
Continuous ¹	-	I _L	-	-	100	mA _{rms} / mA _{DC}
Peak	t=10ms	I _{LPK}	-	-	±350	mA _P
On-Resistance ²	I _L =100mA	R _{ON}	-	30	35	Ω
Off-State Leakage Current	V _L =350V _P	I _{LEAK}	-	-	1	μA
Switching Speeds						
Turn-On	I _F =5mA, V _L =10V	t _{on}	-	-	2	ms
Turn-Off		t _{off}	-	-	1	
Output Capacitance	I _F =0mA, V _L =50V, f=1MHz	C _{OUT}	-	9	-	pF
Input Characteristics						
Input Control Current to Activate ³	I _L =100mA	I _F	-	0.8	2	mA
Input Control Current to Deactivate	-	I _F	0.3	0.7	-	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.36	1.5	V
Reverse Input Current	V _R =5V	I _R	-	-	10	μA
Input to Output Characteristics						
Capacitance, Input to Output	V _{IO} =0V, f=1MHz	C _{IO}	-	0.7	1.45	pF

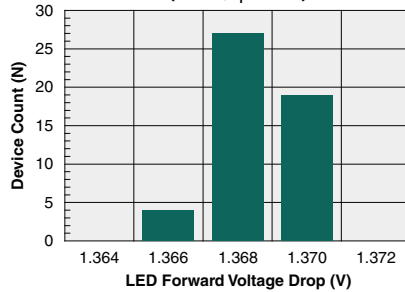
¹ Load current derates linearly from 100mA @ 25°C to 70mA @ 85°C.

² Measurement taken within 1 second of on-time.

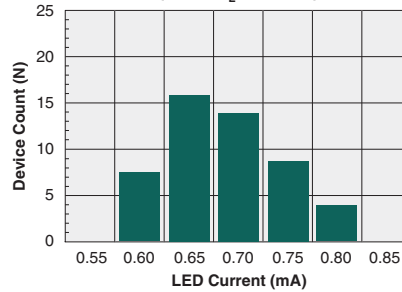
³ For applications requiring high temperature operation (greater than 60°C) a minimum LED drive current of 4mA is recommended.

PERFORMANCE DATA*

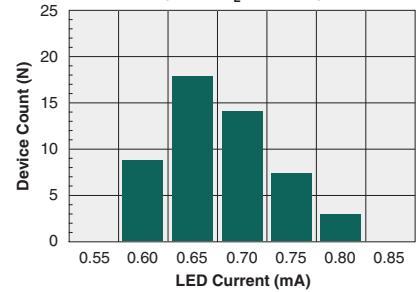
Typical LED Forward Voltage Drop
(N=50, $I_F=5\text{mA}$)



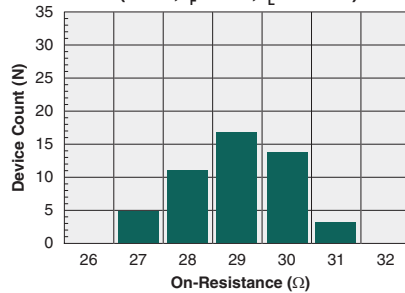
Typical I_F for Switch Operation
(N=50, $I_L=100\text{mA}$)



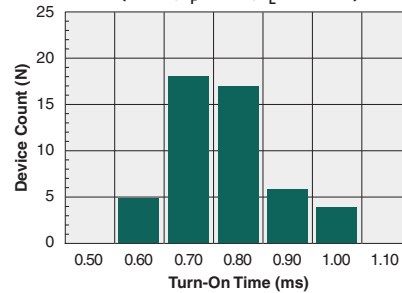
Typical I_F for Switch Dropout
(N=50, $I_L=100\text{mA}$)



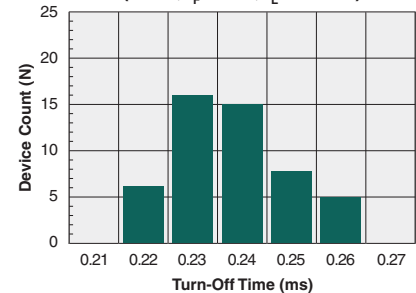
Typical On-Resistance Distribution
(N=50, $I_F=2\text{mA}$, $I_L=100\text{mA}$)



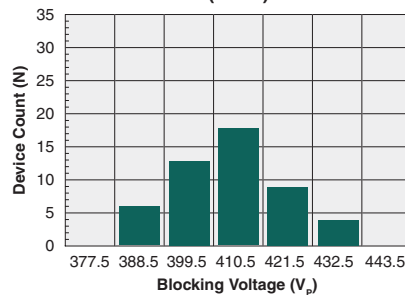
Typical Turn-On Time
(N=50, $I_F=5\text{mA}$, $I_L=100\text{mA}$)



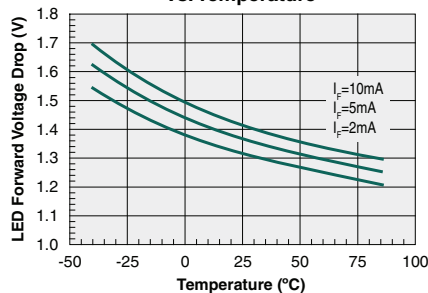
Typical Turn-Off Time
(N=50, $I_F=5\text{mA}$, $I_L=100\text{mA}$)



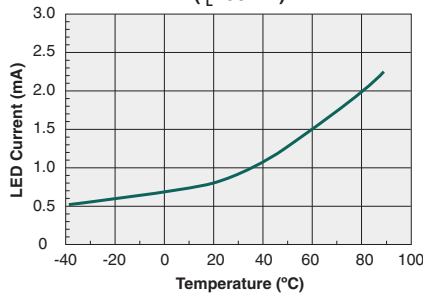
Typical Blocking Voltage Distribution
(N=50)



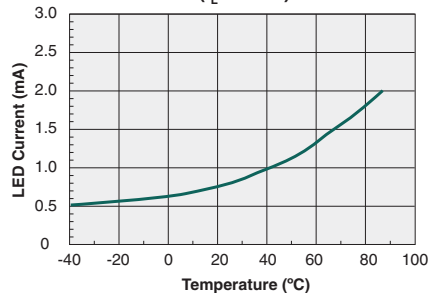
Typical LED Forward Voltage Drop
vs. Temperature



Typical I_F for Switch Operation
vs. Temperature
($I_L=50\text{mA}$)



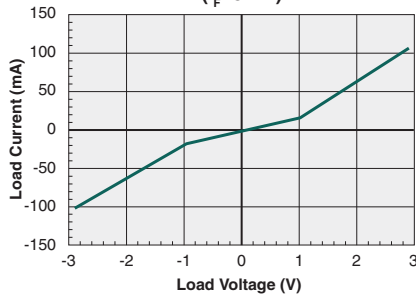
Typical I_F for Switch Dropout
vs. Temperature
($I_L=50\text{mA}$)



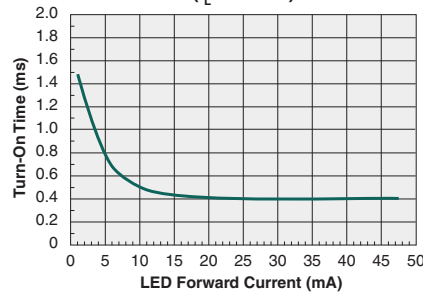
*Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C.

PERFORMANCE DATA*

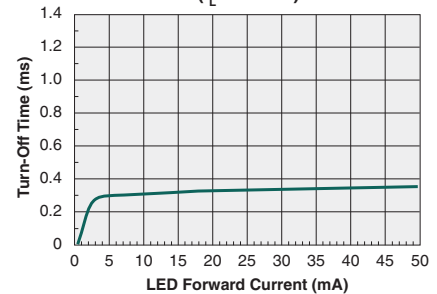
Typical Load Current vs. Load Voltage
($I_F = 5\text{mA}$)



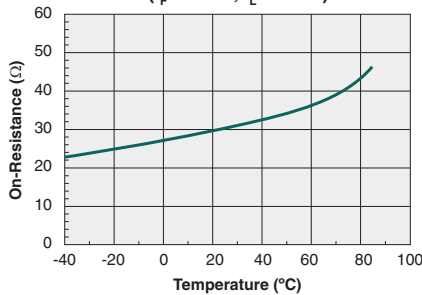
Typical Turn-On Time vs. LED Forward Current
($I_L = 100\text{mA}$)



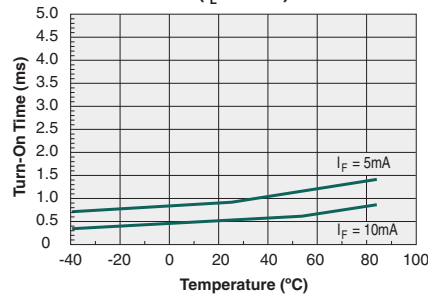
Typical Turn-Off Time vs. LED Forward Current
($I_L = 100\text{mA}$)



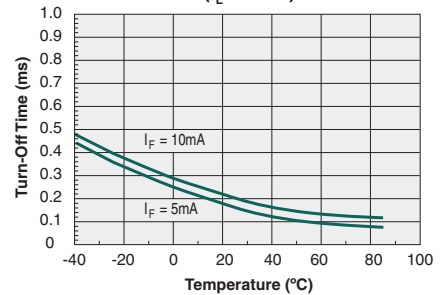
Typical On-Resistance vs. Temperature
($I_F = 10\text{mA}$, $I_L = 50\text{mA}$)



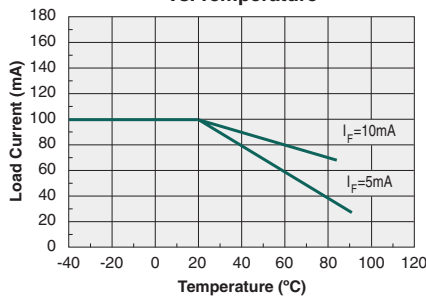
Typical Turn-On Time vs. Temperature
($I_L = 50\text{mA}$)



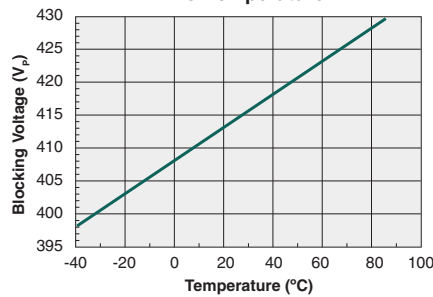
Typical Turn-Off Time vs. Temperature
($I_L = 50\text{mA}$)



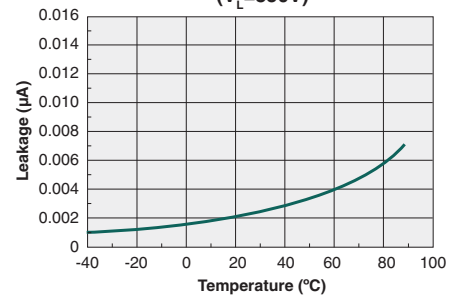
Typical Maximum Load Current vs. Temperature



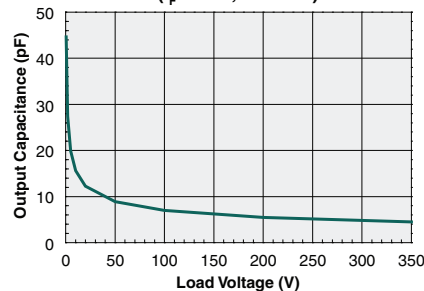
Typical Blocking Voltage vs. Temperature



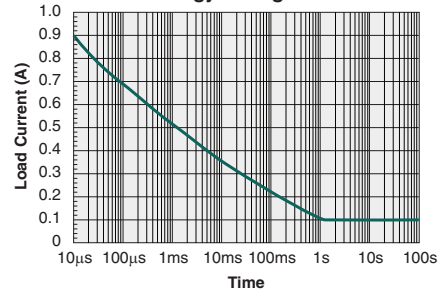
Typical Leakage vs. Temperature
Measured Across Pins 3&4
($V_L = 350\text{V}$)



Output Capacitance vs. Load Voltage
($I_F = 0\text{mA}$, $f = 1\text{MHz}$)



Energy Rating Curve



*Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C.

Manufacturing Information

Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits classifies its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL)** classification as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Classification
CPC1035N	MSL 3

ESD Sensitivity



This product is ESD Sensitive, and should be handled according to the industry standard **JESD-625**.

Soldering Profile

Provided in the table below is the **IPC/JEDEC J-STD-020** Classification Temperature (T_C) and the maximum dwell time the body temperature of these surface mount devices may be ($T_C - 5$)°C or greater. The Classification Temperature sets the Maximum Body Temperature allowed for these devices during reflow soldering processes.

Device	Classification Temperature (T_C)	Dwell Time (t_p)	Max Reflow Cycles
CPC1035N	260°C	30 seconds	3

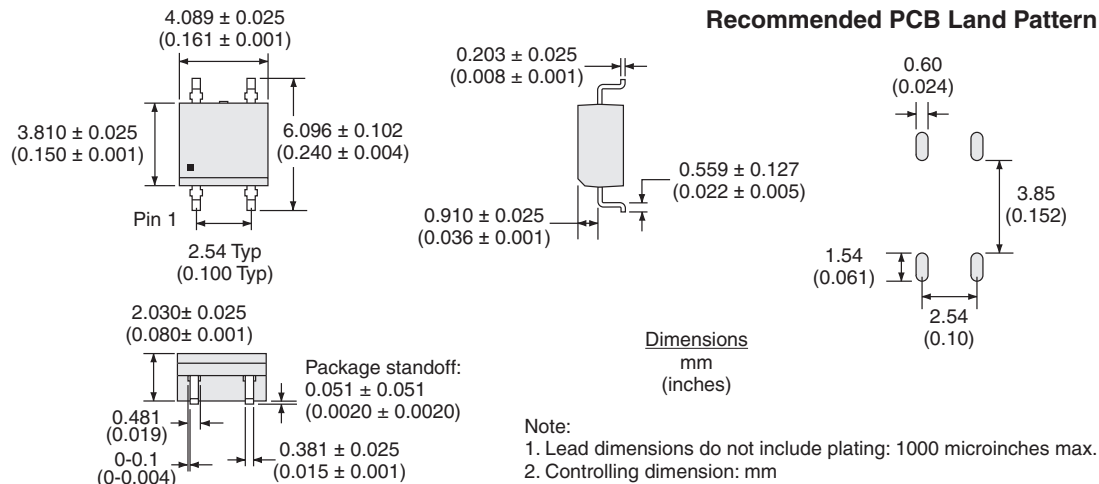
Board Wash

IXYS Integrated Circuits recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to halide flux or solvents.

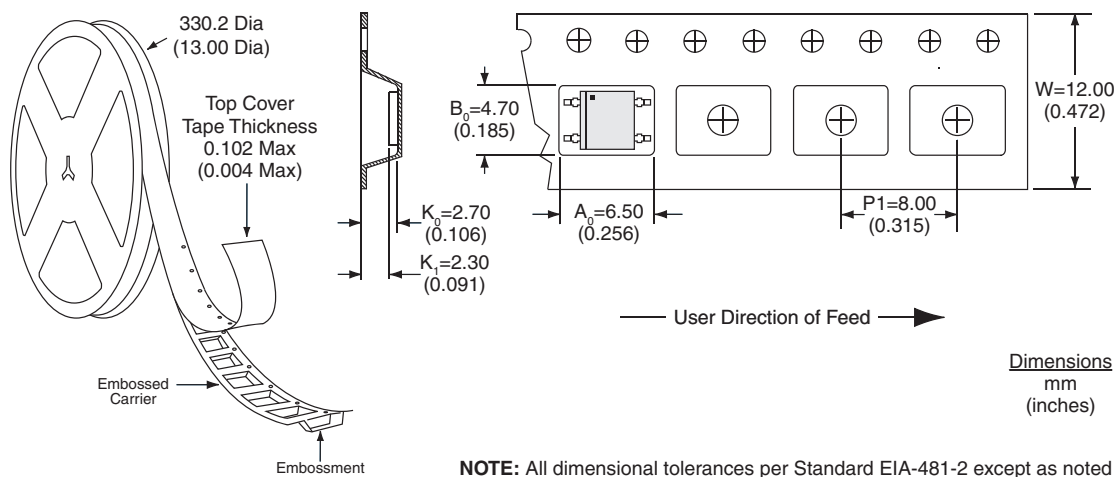


MECHANICAL DIMENSIONS

CPC1035N



CPC1035NTR Tape & Reel



For additional information please visit our website at: <https://www.ixysic.com>